



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

The rev B is being issued to add the qual summary for the affected devices.

Notification Number:	20260914000.0B	Notification Issued	October 28, 2026
AMC03xx vSense Amplifiers Design Change			

Change Type(s)	Design
ZVEI ID	SEM-DE-01

Notification Details

Description of Change:	
Texas Instruments Incorporated is announcing an information only notification for the AMC03xx vSense Amplifiers die update.	
A die revision update as a result of the design change.	
Die Rev:	
Current	New
Die Rev [2P]	Die Rev [2P]
C	D
Reason for Change:	Change to improve yield in the ATE test for noise outliers at cold temperatures.

Anticipated impact on Form, Fit, Function, Quality or Reliability:	These devices include new die with schematic or behavior changes. No change to form or fit. No change to the datasheet parameters.
Changes to product identification resulting from this PCN:	<p>Sample product shipping label (not actual product label):</p>

Products Affected:			
AMC0211DDR	AMC0311DDWVR	AMC0330SDWVR	AMC0381D10DFXR
AMC0211DQDRQ1	AMC0330SDWVR	AMC0330SQDWVRQ1	AMC0381D10QDFXRQ1
AMC0211RDR	AMC0311DQDWVRQ1	AMC0380D04DFXR	AMC0381D16DFXR
AMC0211RQDRQ1	AMC0311RDWVR	AMC0380D04QDFXRQ1	AMC0381D16QDFXRQ1
AMC0211SDR	AMC0311RQDWVRQ1	AMC0380D06DFXR	AMC0381R06DFXR
AMC0211SQDRQ1	AMC0311SDWVR	AMC0380D06QDFXRQ1	AMC0381R06QDFXRQ1

AMC0230DDR	AMC0211DDR	AMC0380R04DFXR	AMC0381R10DFXR
AMC0230DQDRQ1	AMC0311SQDWVR Q1	AMC0380R04QDFXR Q1	AMC0381R10QDFXRQ 1
AMC0230RDR	AMC0330DDWVR	AMC0380R06DFXR	AMC0381R16DFXR
AMC0230RQDRQ1	AMC0330DQDWVR Q1	AMC0380R06QDFXR Q1	AMC0381R16QDFXRQ 1
AMC0230SDR	AMC0330RDWVR	AMC0381D06DFXR	AMC0311DDWVR
AMC0230SQDRQ1	AMC0330RQDWVR Q1	AMC0381D06QDFXR Q1	

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 01-September-2026
Product Attributes

Attributes	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0303M251QDWVRQ1	QBS Package, Process, Product Reference: AMC0311DQDWVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Power Management	Signal Chain	Signal Chain	Signal Chain
Wafer Fab Supplier	RFAB, MH8	MH8, DMOS6	RFAB	MH8, DMOS6	RFAB, MH8	RFAB, MH8
Assembly Site	MLA	MLA	UTL1	TAI	MLA	MLA
Package Group	SOIC	SOIC	QFN	SOIC	SOIC	SOIC
Package Designator	DWV	D	RHD	DWV	DWV	DWV
Pin Count	8	8	28	8	8	8

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device AMC0311DQDWVRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0303M251QDWVRQ1	QBS Package, Process, Product Reference: AMC0311DQDWVRQ1
Test Group A - Accelerated Environment Stress Tests													
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	-	-	3/Pass	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
ACUHA	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0303M251QDWVRQ1	QBS Package, Process, Product Reference: AMC0311DQDWVRQ1
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	-
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	-	1/5/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-
Test Group B - Accelerated Lifetime Simulation Tests													
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	1000 Hours	-	-	3/231/0	-	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	-	-	3/231/0	1/77/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	3/2400/0	-	-
Test Group C - Package Assembly Integrity Tests													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	-	-	-	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	-	-	-	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	1/10/0
Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDOB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0303M251QDWVRQ1	QBS Package, Process, Product Reference: AMC0311DQDWVRQ1
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests													
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	Corner pins	1000 Volts	1/3/0	-	-	-	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	-	-	-	-	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	-	-	-	-	3/90/0
Additional Tests													

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I): -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold: HTOL, ED
- Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room: AC/uhAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2604-087

Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 0.8 mil Cu Wire at MLA
Approve Date 07-May-2025

Attributes	Qual Device: AMC0303M251QDWVRQ1
Automotive Grade Level	Grade 1
Operating Temp Range (C)	-40 to 125
Product Function	Signal Chain
Wafer Fab Supplier	DMOS6, MH8
Assembly Site	MLA
Package Group	SOIC
Package Designator	DWV
Pin Count	8

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0303M251QDWVRQ1
Test Group A - Accelerated Environment Stress Tests								
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	3/Pass
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	3/210/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	3/9/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0303M251QDWVRQ1
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/210/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	3/3/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device AMC0303M251QDWVRQ1 is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
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E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2305-121

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